

AOS Semiconductor Product Reliability Report

AOZ17517QI-02 rev A

Plastic Encapsulated Device

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The AOS product reliability report summarizes the qualification results for AOZ17517QI-02 in QFN5x5A 32L package. Accelerated environmental tests are performed on a specific sample size, samples are electrically tested before and after each stress time point. Review of final electrical test results confirm that AOZ17517QI-02 pass the AOS guality and reliability requirements. The released products will be categorized by its process family and routinely monitored for continuous improvement of product quality.

| Test Item | Test Condition | Time Point | Sample Size / Lots | Number of Failures | Reference Standard |
|-----------------------------|---|---------------------------|-----------------------|-----------------------|-----------------------|
| HTOL | T」= 125°C, V _{IN} = 24V | 168 / 500 / 1000 hours | 231 pcs (3 lots) | 0 | JESD22-A108 |
| Preconditioning (Note A) | TA = 30°C, RH = 60% + 3 cycle reflow @ 260°C (MSL 3) | 192 hours | 924 pcs (3 lots) | 0 | JESD22-A113 |
| HAST | T _A = 130°C, RH = 85%, P = 33.3psia, V _{IN} = 20V | 96 hours | 231 pcs (3 lots) | 0 | JESD22-A110 |
| Temperature Cycle | T _A = -65°C to 150°C, air to air | 500 / 1000 cycles | 231 pcs (3 lots) | 0 | JESD22-A104 |
| HTSL | T _A = 150°C | 1000 hours | 231 pcs (3 lots) | 0 | JESD22-A103 |
| Autoclave | T _A = 121°C, RH = 100%, P =29.7psia | 96 hours | 231 pcs | 0 | JESD22-A102 |
| HTGB (MOSFET) | T _J = 150°C, V _{GS} = 10V | 168 / 500 /1000 hours | 231 (3 lots) | 0 | JESD22-A108 |
| HTRB (MOSFET) | TJ = 150°C, VDS = 28.5V | 168 / 500/1000 hours | 231 (3 lots) | 0 | JESD22-A108 |

I. AOZ17517QI-02 Reliability Stress Test Summary and Results

Note: The reliability data presents total of available generic data up to the published date. Note A: MSL (Moisture Sensitivity Level) 3 based on J-STD-020

II. Reliability Evaluation

The presentation of FIT rate for the individual product reliability is restricted by the actual burn-in sample size of the product technology. Failure Rate Determination is based on JEDEC Standard JESD 85.

FIT rate (failures per billion device hours): 1.393

MTTF = 717.9 million hrs=81952.622 years

Condition: $V_0 = 20V$, $T_0 = 55^{\circ}C$, $V_{s(IC)} = 24V$, $V_{s(MOSFET)} = 28.5V$, $T_{s(IC)} = 125^{\circ}C$ and $T_{s(MOSFET)} = 150^{\circ}C$ Accumulated Sample Size x Hours: MOSFET = 480,000, IC = 1,240,320

| $\lambda = \chi^2$ [CL,(2f+2)]/2 x [1/(SS x t x AF)]; [equation 1] where CL = % of confidence level | |
|---|--|
| f = number of failure SS = sample size t = stress time | |

Looking up the $\chi^2/2$ table for zero failure (burn-in) with 60% confidence, the value of χ^2 [CL,(2f+2)]/2 is 0.92.

The Acceleration Factor (AF) is calculated from the following formula (both temperature and voltage acceleration factors are used in the final acceleration factor calculation) : E_a = activation energy

 $AF = AF_T \times AF_V = \exp[(E_a/k) \times (1/T_0-1/T_s)] \times \exp[\beta (Vs-Vo)]$ where



- k = Boltzmann constant
- $T_o = operating T_J$
- $T_s = stress T_J$
- V_s = stress voltage
- V_{\circ} = operating voltage
- β = voltage acceleration coefficient

Assuming typical operating environment, $V_0 = 20V$, $T_0 = 55^{\circ}C$, $E_a = 0.7eV$, $V_{s(IC)} = 24V$, $V_{s(MOSFET)} = 28.5V$, $T_{s(IC)} = 125^{\circ}C$ and $T_{s(MOSFET)} = 150^{\circ}C$, $\beta = 0.5$ (silicon defect)

$$AF(DriverIC) = exp\left[\left(\frac{0.7}{8.617E - 5}\right) \bullet \left(\frac{1}{273 + 55} - \frac{1}{273 + 125}\right)\right] \bullet exp\left[0.5 \bullet (24V - 20V)\right]$$
$$AF(MOSFET) = exp\left[\left(\frac{0.7}{8.617E - 5}\right) \bullet \left(\frac{1}{273 + 55} - \frac{1}{273 + 150}\right)\right] \bullet exp\left[0.5 \bullet (28.5V - 20V)\right]$$

Substituting the values in equation 1, we have

$$\lambda = 0.92 \bullet \frac{1}{\text{sample Size} \bullet \text{Stress Duration} \bullet AF(MOSFET)} + \frac{1}{\text{sample Size} \bullet \text{Stress Duration} \bullet AF(DriverIC)} hr^{-1}$$

 λ = 1.393 10⁻⁹ hr ⁻¹ or 1.393 FIT; MTTF = (1/ λ) = 717.9 million hrs = 81952.622 years

The calculation shows failure rate is 1.393 FIT, MTTF is 717.9 million hours under typical operating conditions.

III. AOZ17517QI-02 ESD and Latch Up Test Results

| Test | Test Conditions | Total Sample Size | Number of Failures | Reference Standard |
|---|---|-------------------------|-----------------------|-----------------------|
| Electrostatic Discharge Human Body Model | T _A = 25°C, +/-2kV | 10 | 0 | JESD-A114 |
| Electrostatic Discharge Charged Device Model | T _A = 25°C, +/-1kV | 10 | 0 | JESD-C101 |
| Latch Up | T _A = 25°C, +/-200mA, 1.27x OV | 10 | 0 | JESD78 |
| Latch Up | T _A = 125°C, +/-200mA, 1.27x OV | 10 | 0 | JESD78 |

Note: ATE results are used to determine PASS/FAIL. Parametric shift<10%.

